

GENERAL NOTES
 allgemeine Bemerkungen

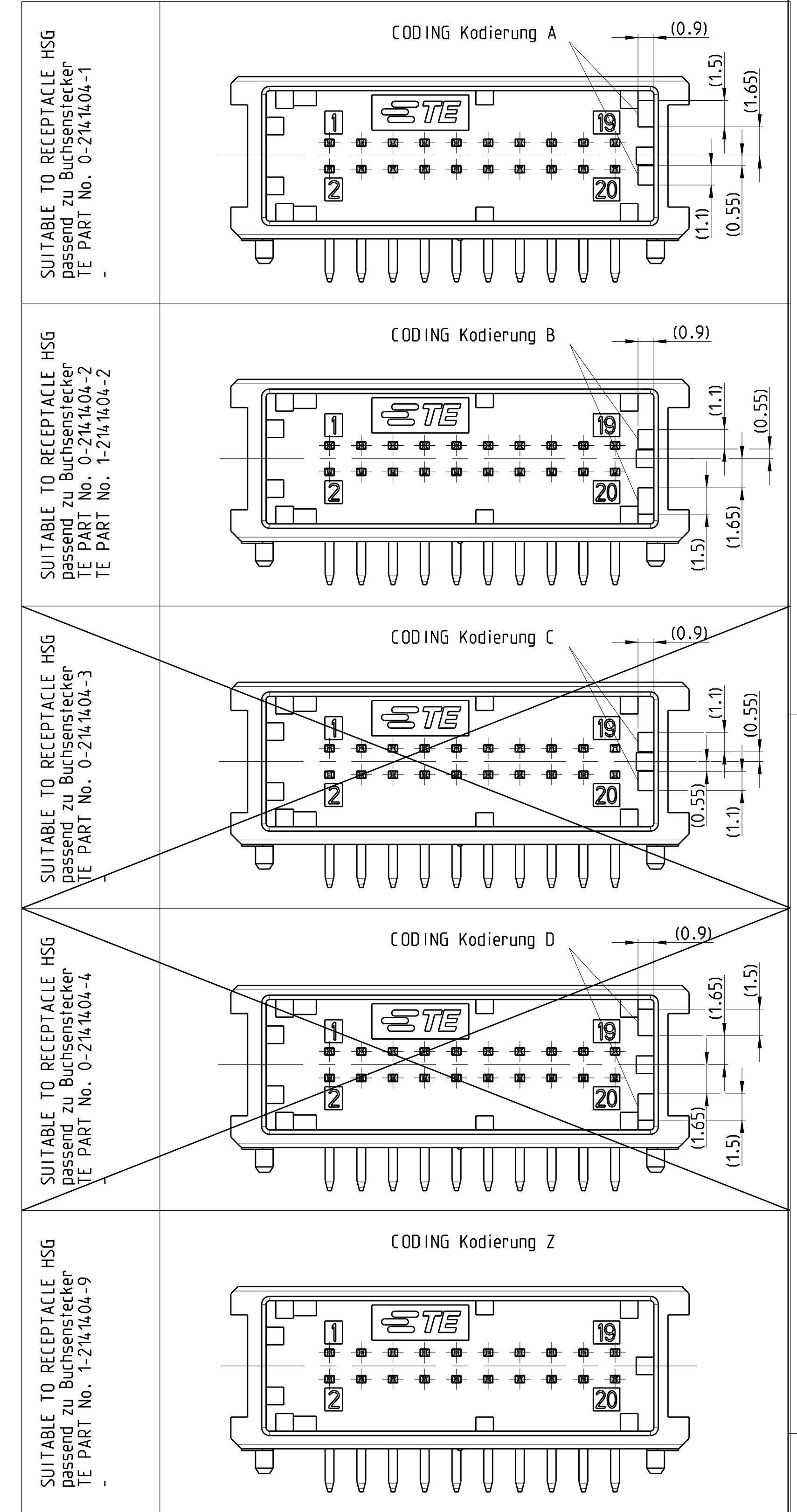
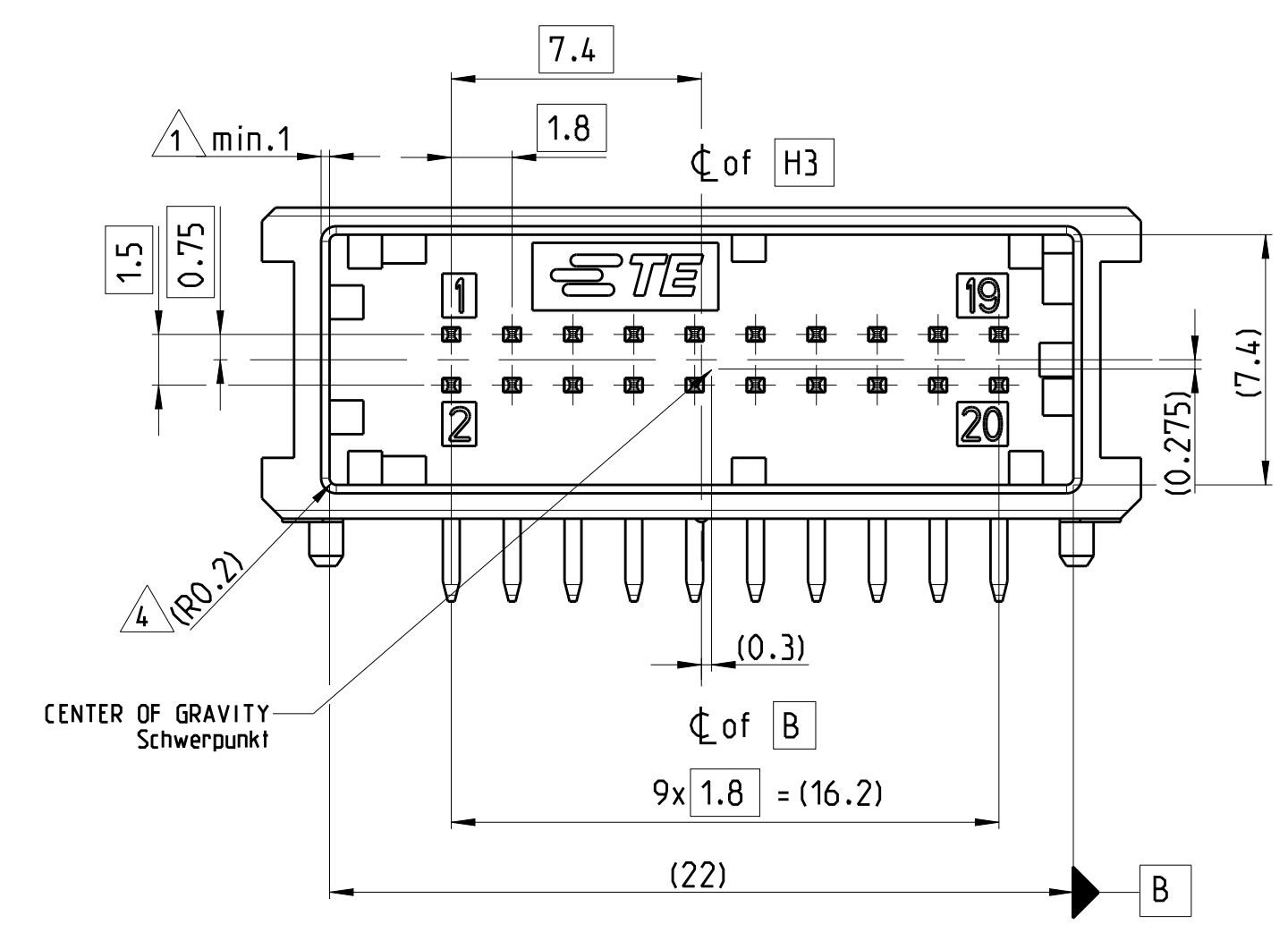
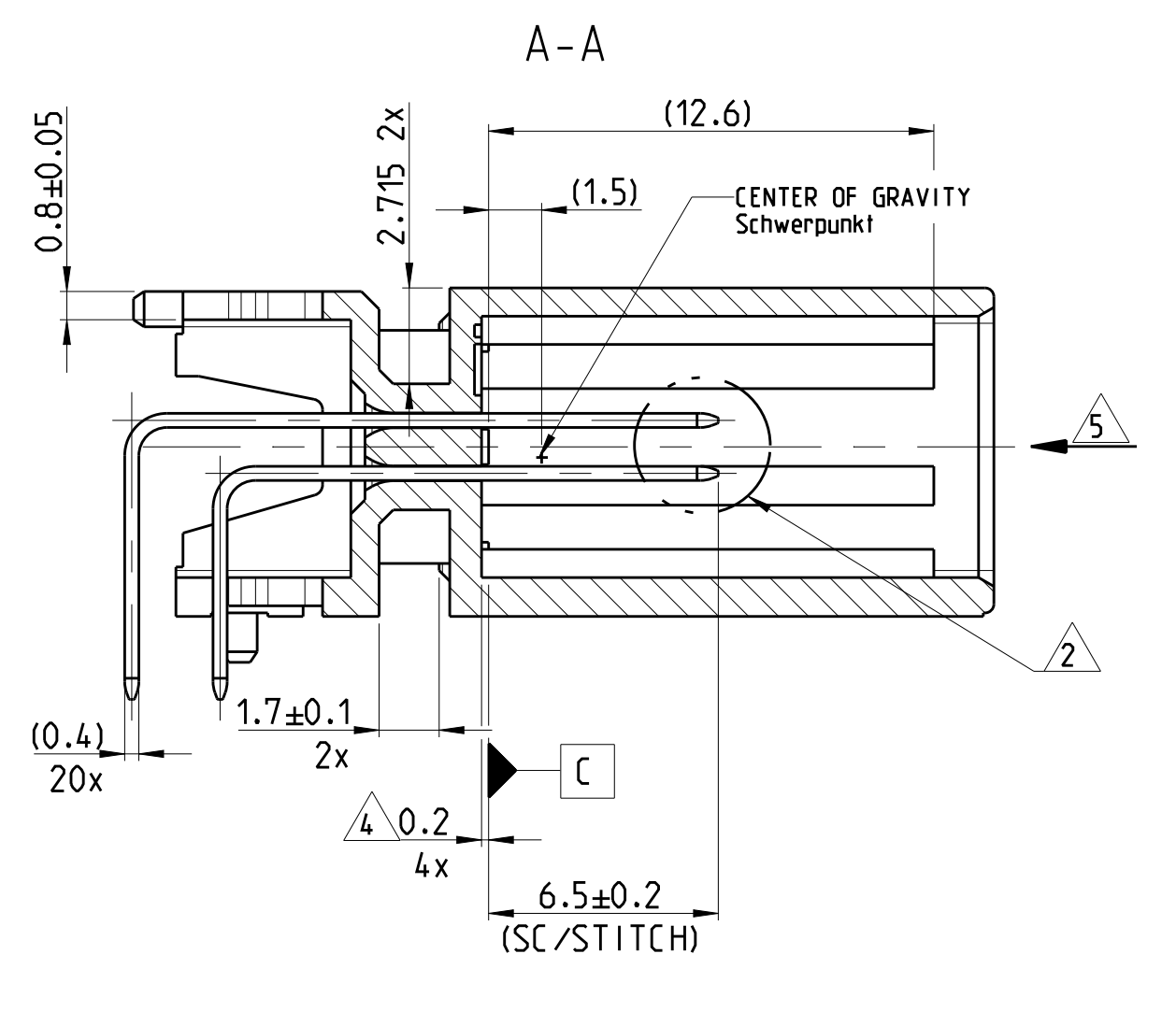
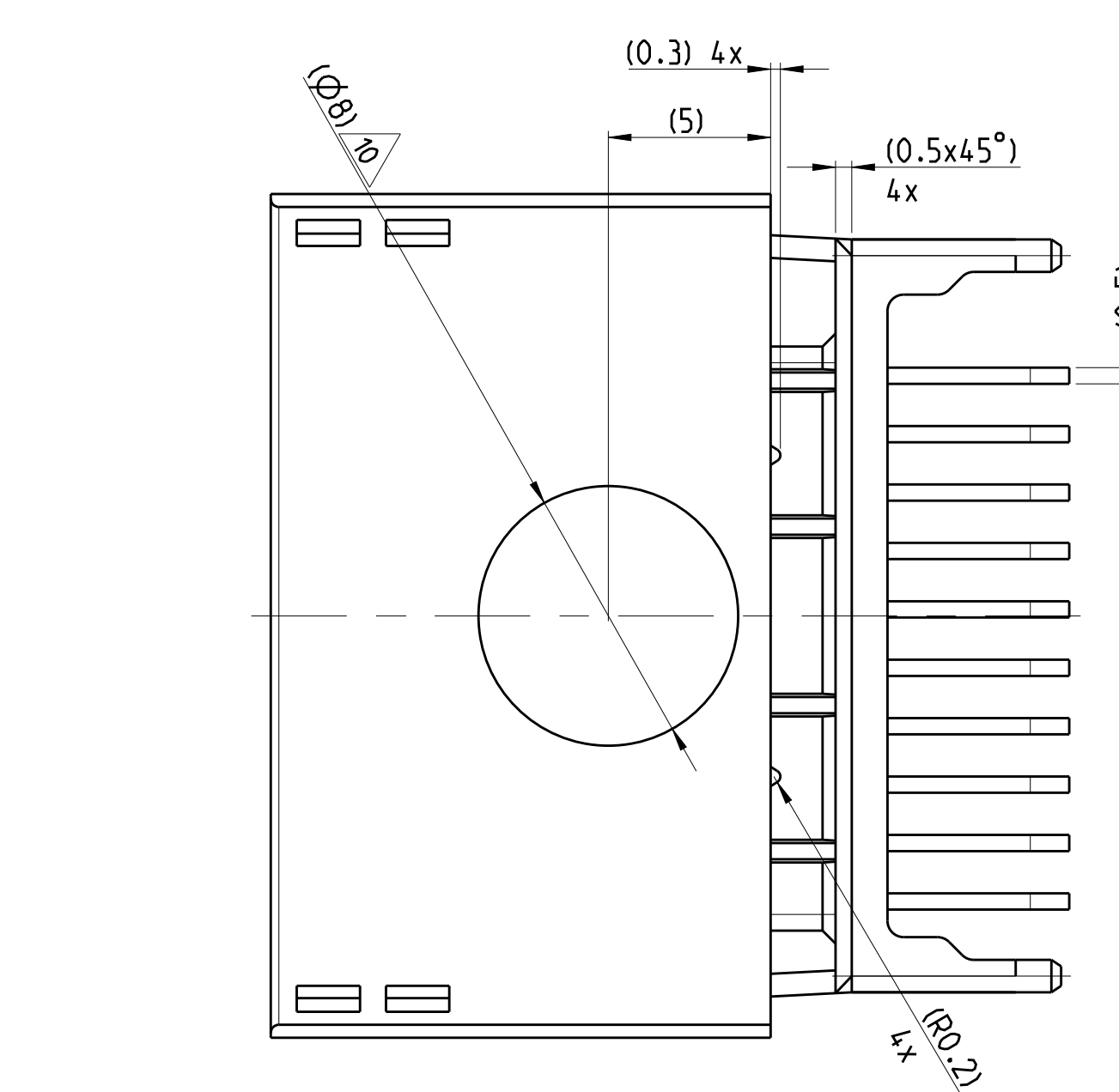
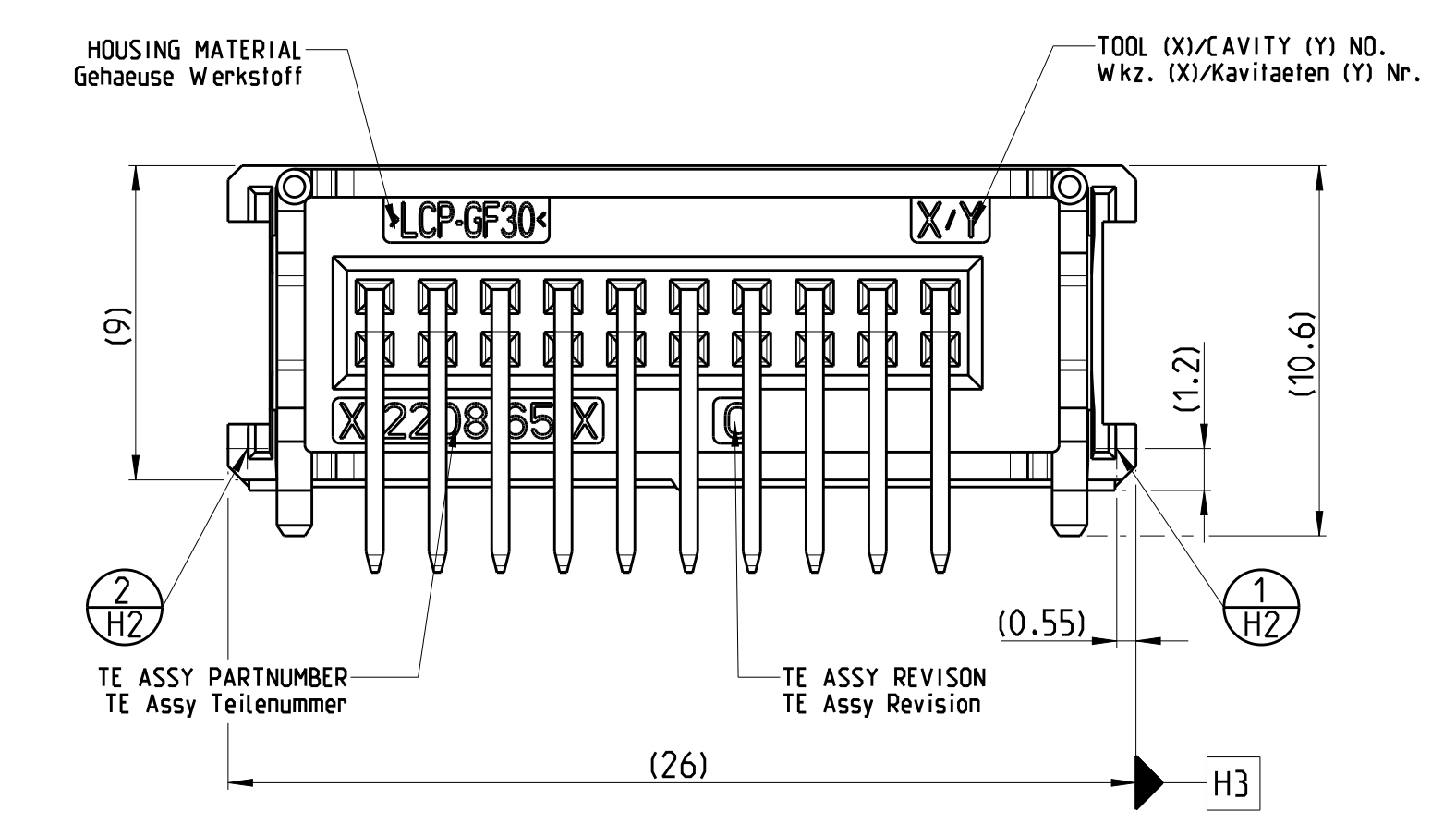
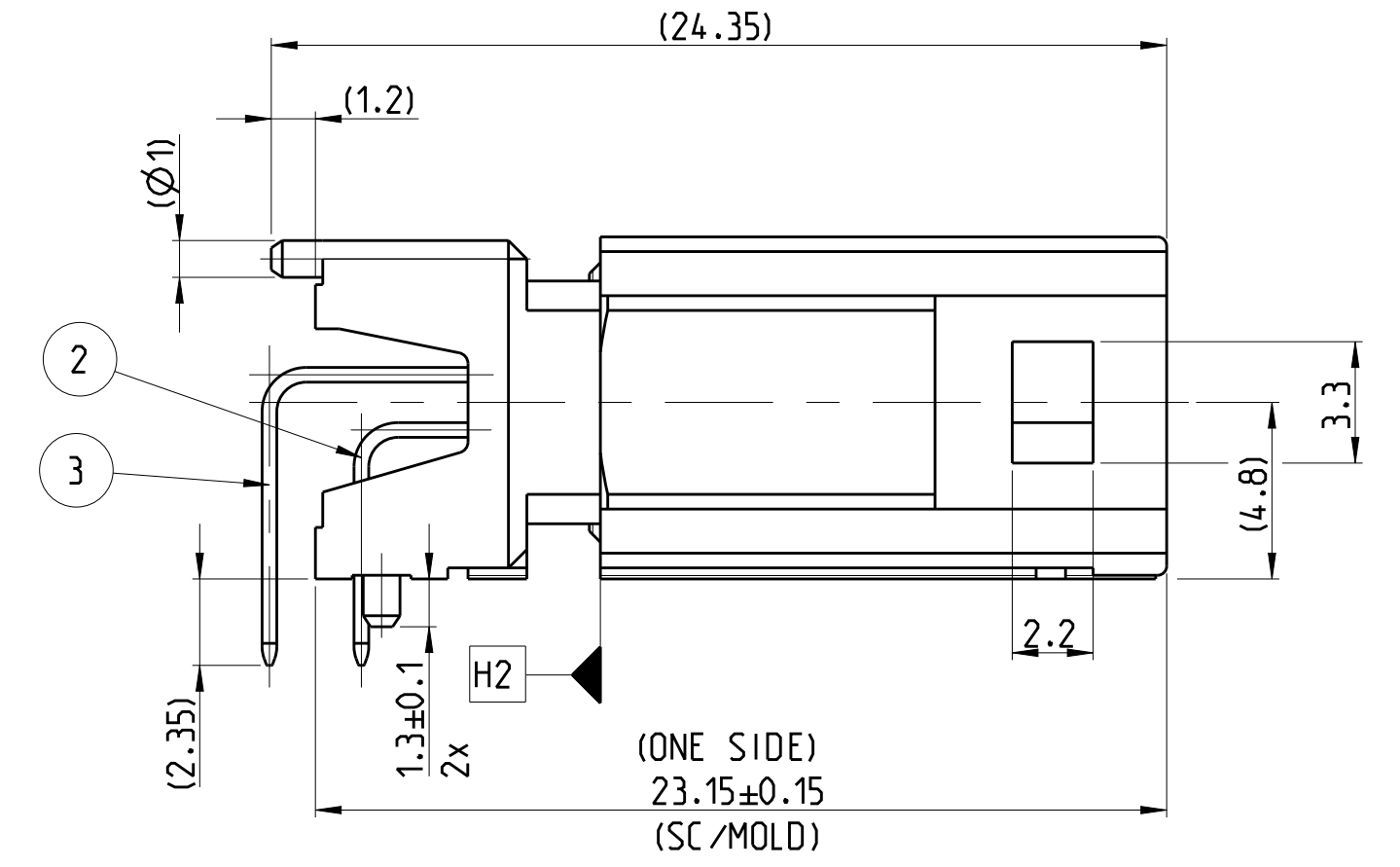
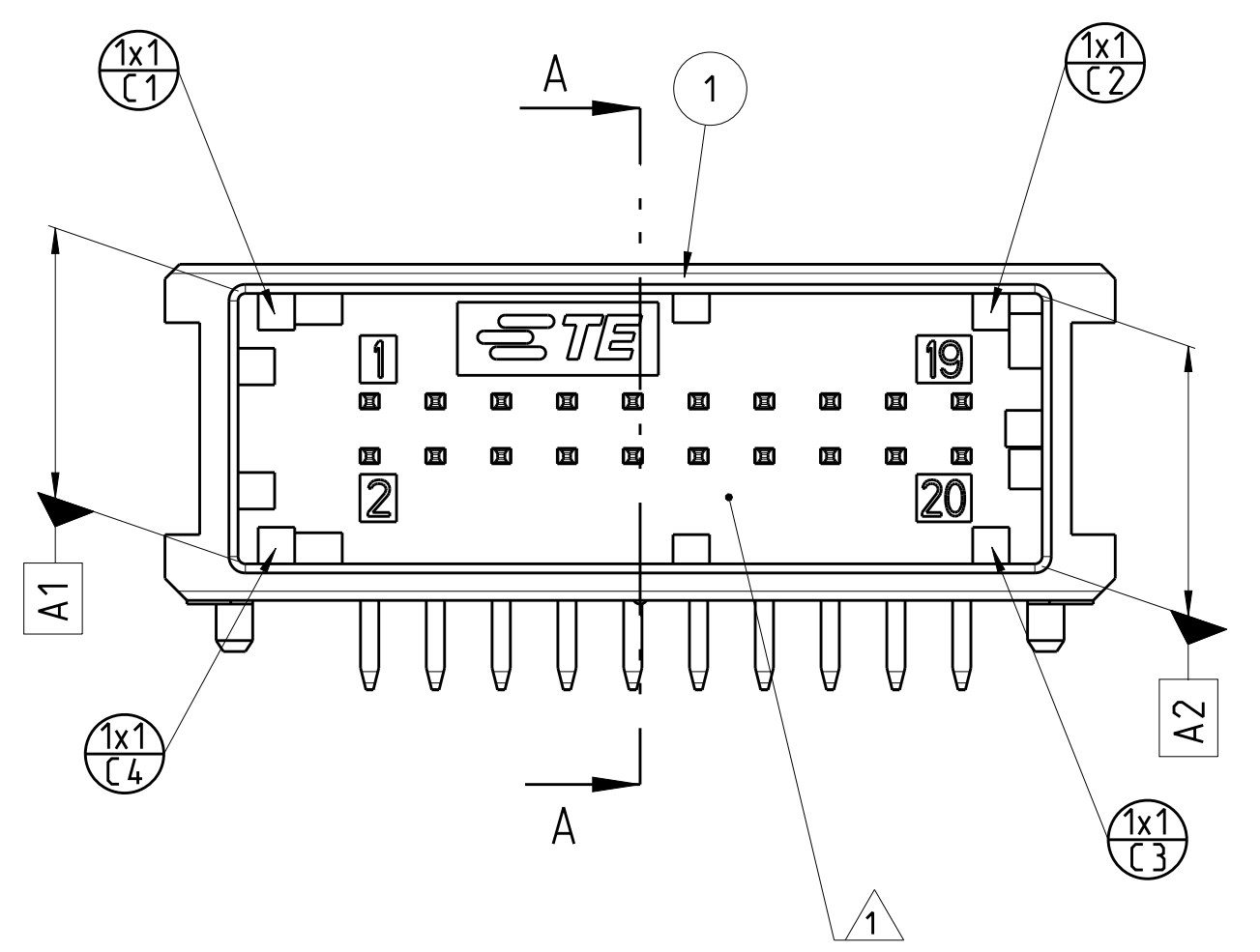
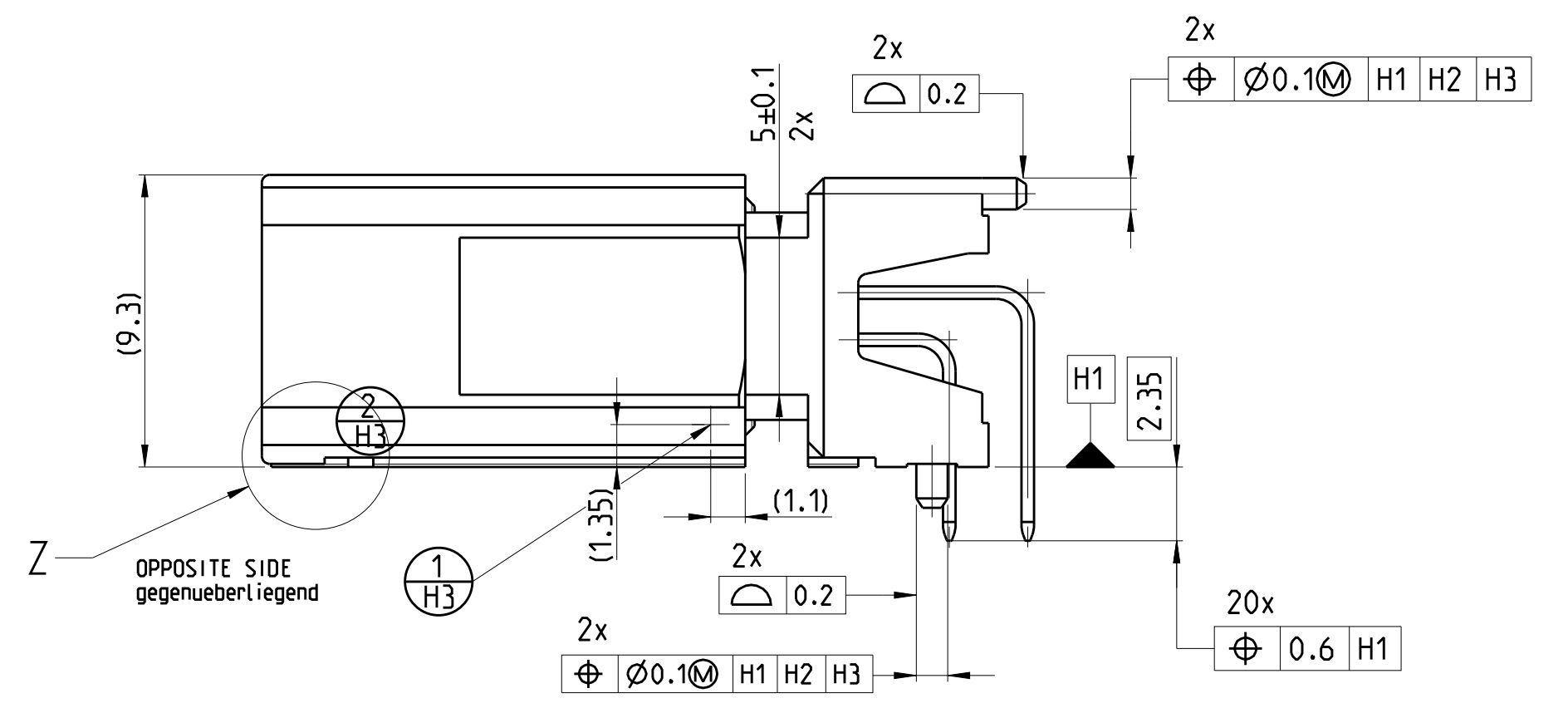
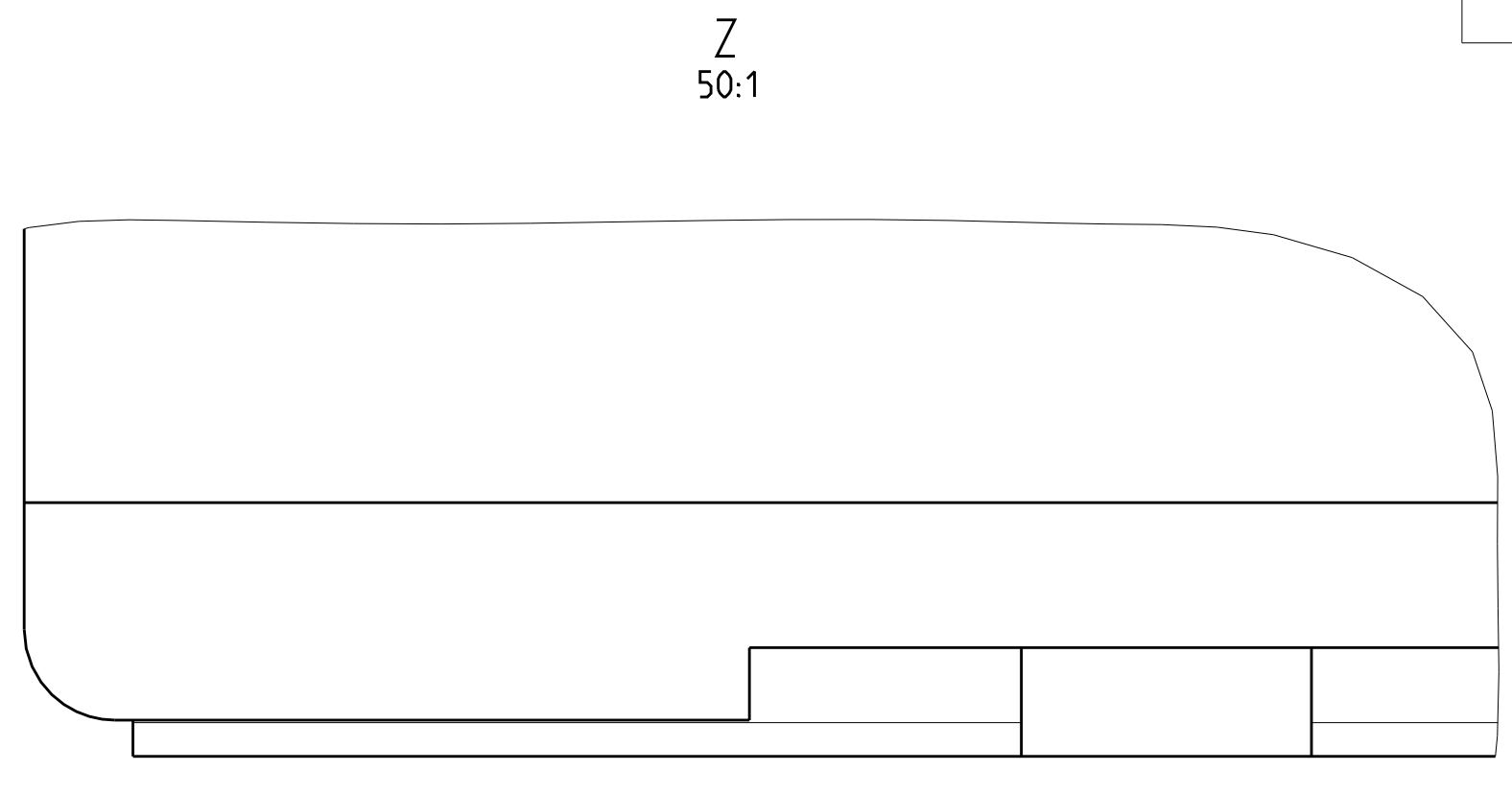
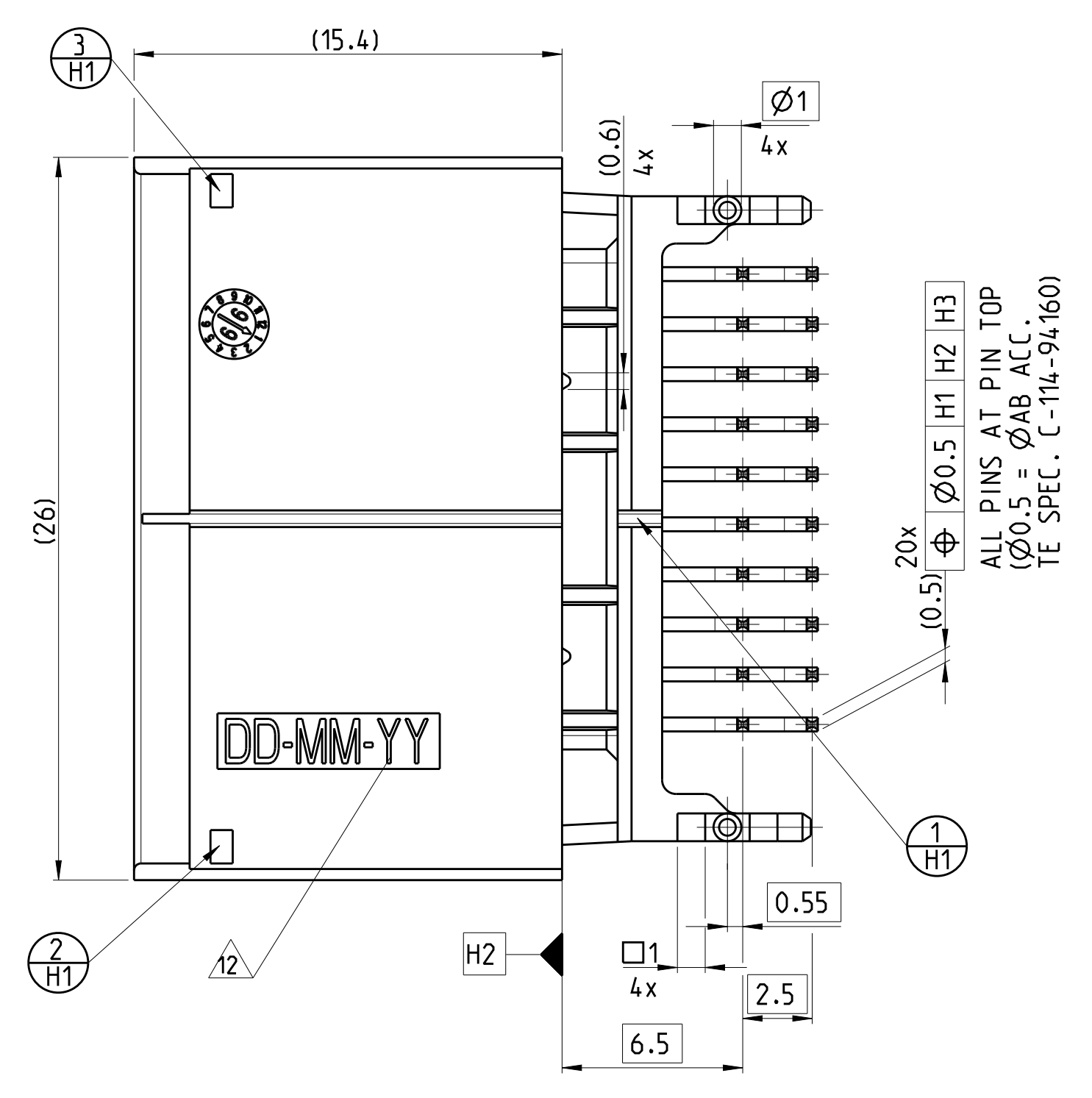
HEADER DESIGN BASED ON PLATFORM DESIGN OF "NANO-MQS MARKET SERIES"
 ACC. TE SPECIFICATION C-114-94.160

Stiftwandendesign basiert auf Plattformdesign der "Nano-MQS Market Serie"
 gem. TE Spezifikation C-114-94.160

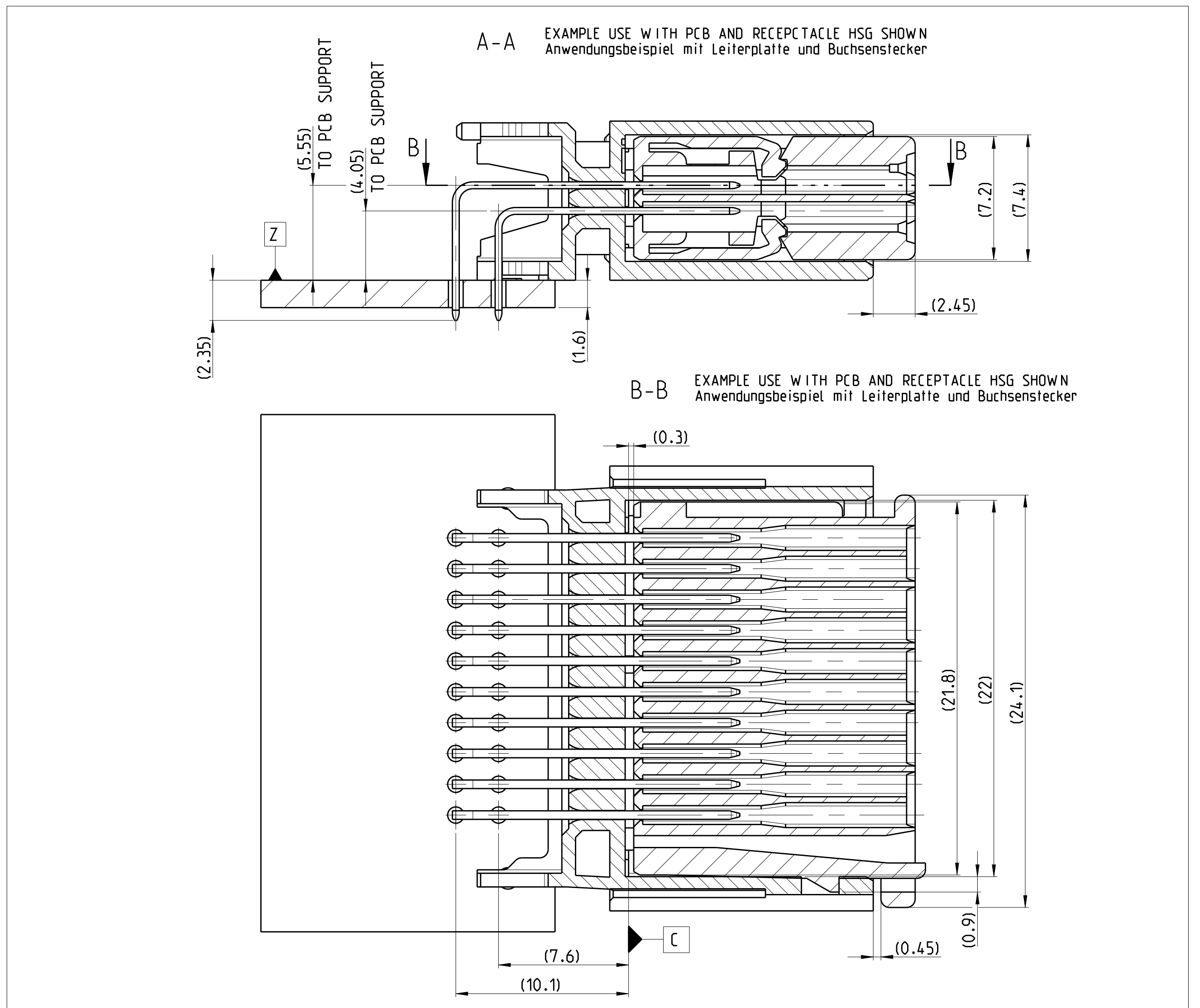
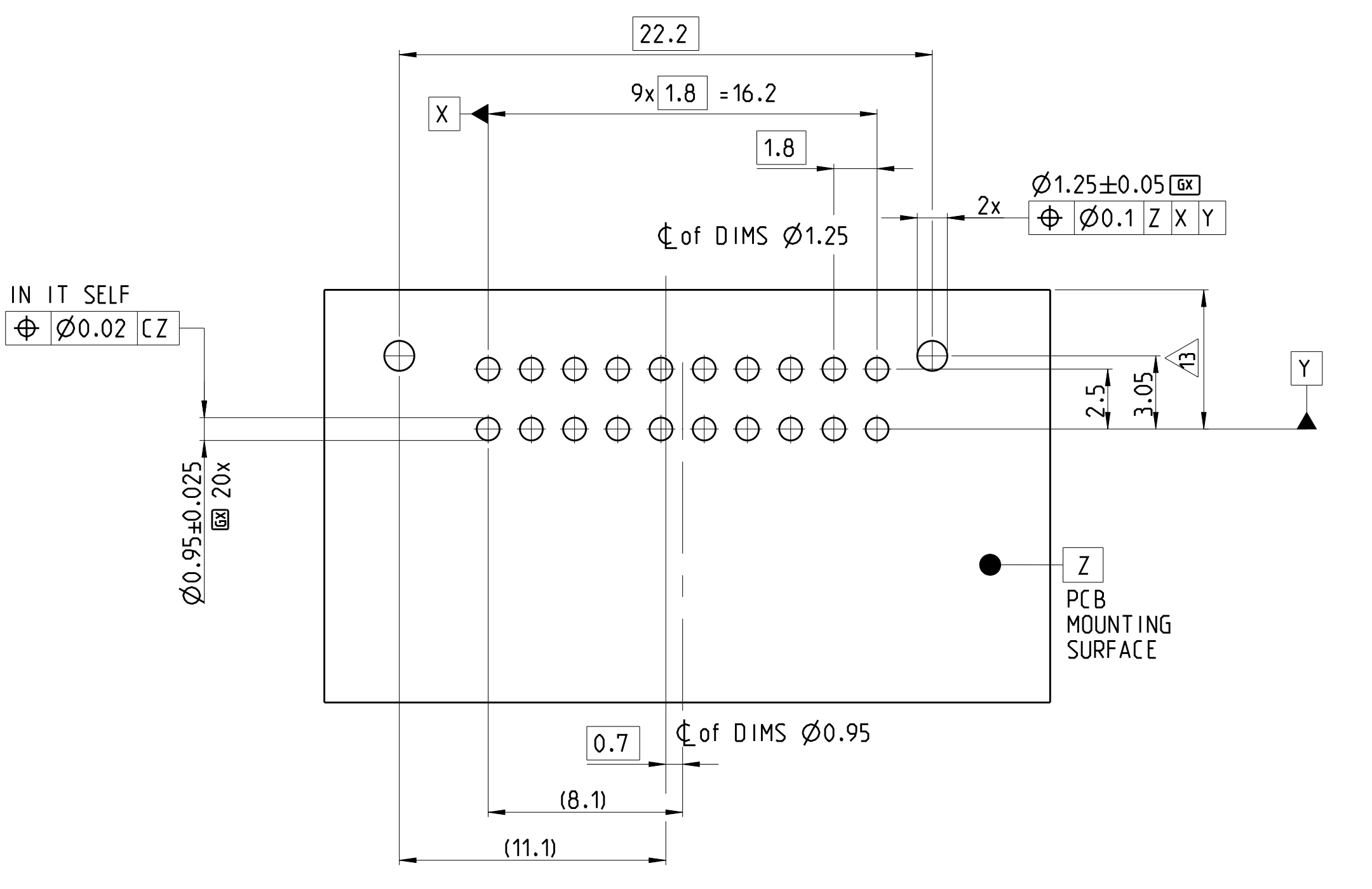
DATUMS I1, I2, I3 = INTERFACE --- HERE: A, B, C
 DATUMS H1, H2, H3 = HEADER

- NOTES**
 Bemerkungen
- ⚠ MISSING DIMENSIONS SEE TE SPECIFICATION 114-94000-11
 Fehlende Maße siehe TE Spezifikation 114-94000-11
 - ⚠ CONTACT AREAS ACC. TE SPECIFICATION 114-94201
 Kontaktbereiche gem. TE Spezifikation 114-94201
 - ⚠ PLASTIC MATERIAL WITH 20% REGRIND PORTION
 Polymer-Werkstoff mit 20% Mahlgut-/ Recyclatanteil
 - ⚠ DIFFERING TO
 abweichend zu
 - ⚠ CONTACT PUSH-OUT FORCES $\geq 15N$ IN A RANGE UP TO 0.2MM WITH 50 MM/MIN
 AT A PRELOAD OF 5N; MEASURED AT 1 ASSEMBLY EACH CAVITY
 Kontakt-Ausdruckkräfte $\geq 15N$ in einem Bereich bis 0.2mm gepreßt mit 50mm/min
 bei einer Vorlast von 5N; gemessen an 1 Assemblage je Nest
 - 6 SOLDERABILITY ACC. DIN EN 60068-2-20 AGEING 3B
 Lötbarkeit gem. DIN EN 60068-2-20 Alterung 3b
 - 7 100% ELECTRICAL INSPECTION END OF LINE (EC)
 100% Elektrische Endkontrolle (EC)
 - 8 CLEANLINESS ACC. TO TE SPECIFICATION 115-18390 (INCL. VDA Band 19)
 Sauberkeit gem. TE Spezifikation 115-18390 (inkl. VDA Band 19)
 - 9 PACKAGING: BLISTER-BELT ON REEL
 Verpackung: Blistergurt auf Rolle
 - ⚠ MAX. AREA FOR SUCKING-IN TO PICK & PLACE: 0.1MM FLATNESS
 max. Bereich zum Ansaugen fuer Pick & Place: 0.1mm Ebenheit
 - 11 FONT AREAS AND CHARACTERS MAX. 0.2MM SUNK AND RAISED
 Schriftbereiche und Zeichen max. 0.2mm vertieft und erhaben
 - ⚠ AREA FOR MARKING "INSPECTED GOOD PARTS"
 PER INKJET PRINTING OR LASER MARKING
 Bereich fuer Markierung "geprüfte Gutteile"
 mittels Tintenstrahlbedruckung oder Laserbeschriftung
 - ⚠ RECOMMENDATION BASED ON PART-BALANCE POINT MIN. 15MM
 Empfehlung aufgrund des Teileschwerpunktes min. 15mm

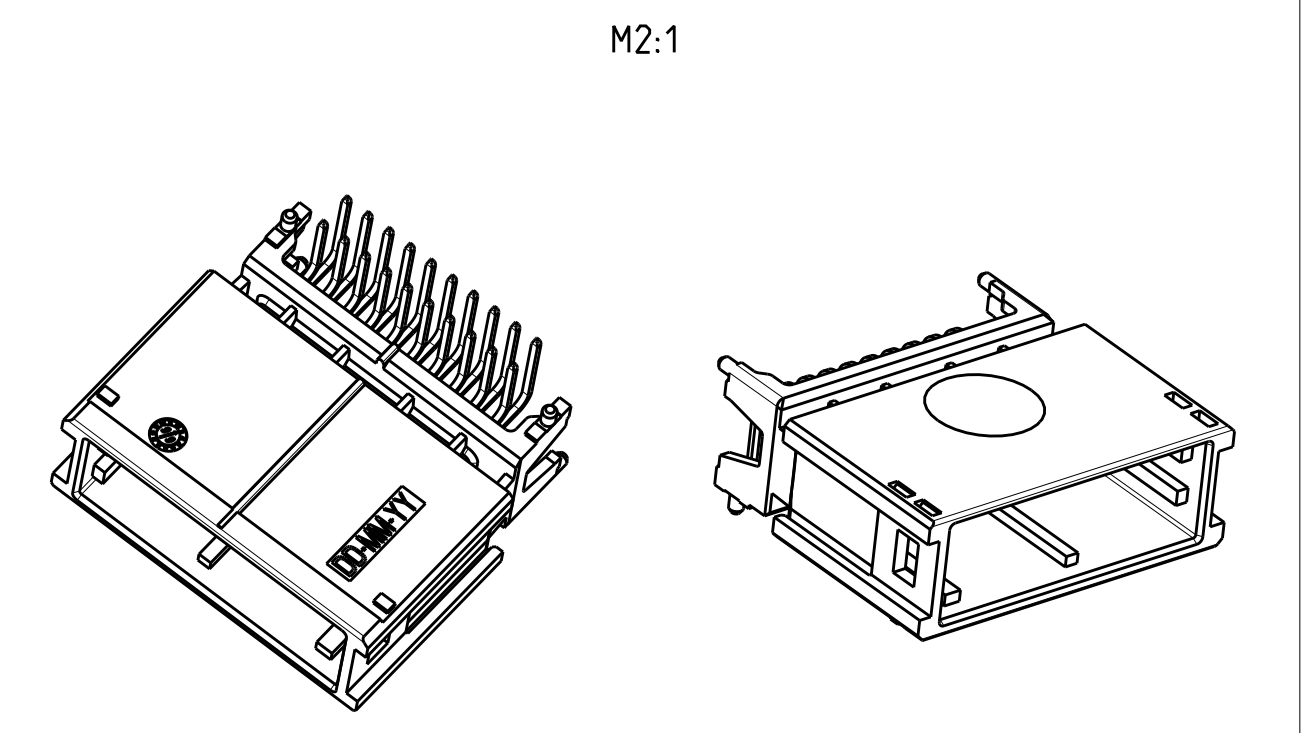
| REV | DATE | DESCRIPTION | BY | APP |
|-----|-------------|---------------------------|-----------|-----------|
| C1 | 30NOV2015 | VARIANT 1-2208165-2 ADDED | MB | BF |
| C2 | 05JUL2016 | NOTES REVISED | HD | SCHD |
| C3 | E-20-002028 | | FRAN | SCHD |
| C4 | | Updated Note 5 | DAKAR2020 | FRAN SCHD |



RECOMMENDED PCB LAYOUT
 empfohlenes Leiterplattenanschlussbild



| QTY PER ASSY | 10 | 10 | 10 | 10 | 1 | 1 | 1 | 1 | 0--9 | 1--2 | 0--2 | 0--1 | | | | | | | |
|--------------|----|----|----|----|---|---|---|---|--------|----------|-----------|-----------|-------------|------|----|--|--|--|--|
| 10 | 10 | 10 | 10 | 10 | 1 | 1 | 1 | 1 | 0--9 | 1--2 | 0--2 | 0--1 | | | | | | | |
| | ⚠ | ⚠ | ⚠ | ⚠ | ⚠ | ⚠ | ⚠ | ⚠ | FINISH | MATERIAL | Werkstoff | Benennung | DESCRIPTION | ITEM | NO | | | | |
| | | | | | | | | | | | | | | | | | | | |



DIFFERENCE DIMENSIONS SPECIFIED ACC. TO DIM MODELS CENTRE TO NOMINAL DIMENSION POSITION
 PRODUKTCHARAKTERISTIKEN ACC. OMP EMEA.12 TOLERANZEN ISO 8015
 BESONDERE MERKMALE NACH OMP EMEA.12 TOLERANZUNG ISO 8015

THIS DRAWING IS A CONTROLLED DOCUMENT.
 W. Dietrich 20 JUN 2012
 M. Schilvogl 20 JUN 2012

TE Connectivity
 20pos., 90DEG. PINHEADER ASSY
 20pol., 90Grad. Stiftwanne Assy
 NANO MQS

SCALE 5:1 SHEET 1 OF 1